

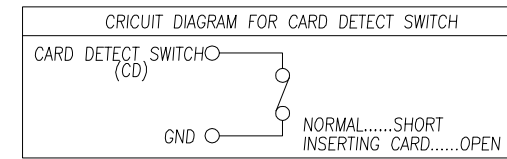
修 订	标 记	修 改 描 要	签 名	日 期
REV NO	MARK	REVISION DESCRIPTION	SIGNATURE	DATE
		NEW DWG		2016-03-12

### Specification

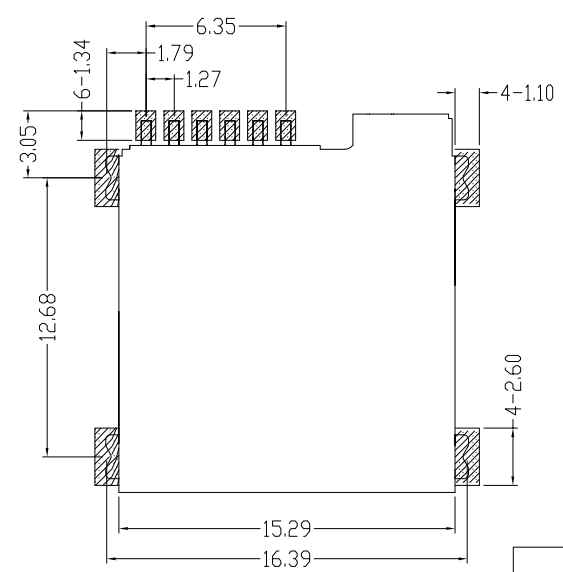
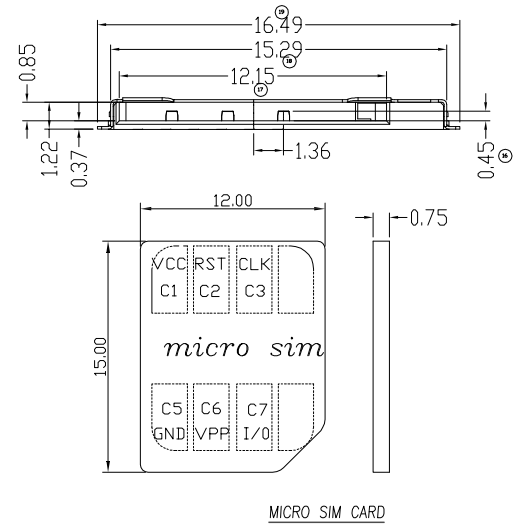
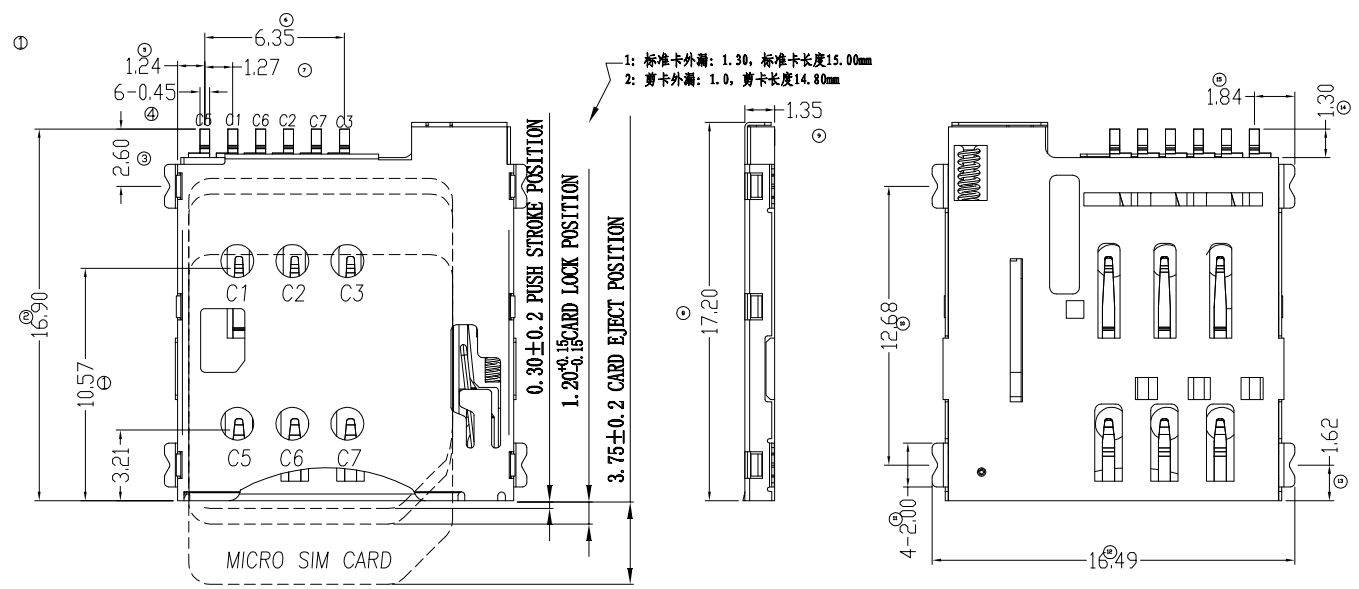
**MATERIAL:**  
 Insulator: High Temperature Thermoplastic, UL 94V-0.  
 Contact: Copper Alloy  
 SHELL: SUS

**PLATING:**  
 Contact: Plated 50u'' Ni Overall Contact Au 1U  
 Shell: Plated 50u'' Ni Overall  
 Plated 1u''Au Selective Contact Area

**Electrical:**  
 Current Rating :0.5mA AC/DC max.  
 Voltage Rating :125V AC/DC  
 Ambient Temperature Range :-20° C~+60° C  
 Storage Temperature Range :-40° C~+70° C  
 Ambient Humidity Range :95% R.H. Max.  
 Contact Resistance:100m Ω max.  
 Insulation Resistance:1000M Ω min./500VDC  
 产品耐温温度: 260° C  
 Mating Cycles:3000Min Insertions



SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05



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-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表		TITLE: 产品名称: MICRO SIM卡座PUSH 1.35H 6P	
X.X ±0.30	X.X* ±3°	APPD: 核准:	PART NO: 产品编号: K-DYX-008
X.XX ±0.20	X.XX* ±2°	CHECK: 校对: 王建业	DATE SCALE UNIT CODE NUMBER
X.XXX ±0.10	X.XXX* ±1°	DRAW: 绘图: 黄艳兰	2016-03-12 1:1 mm A001